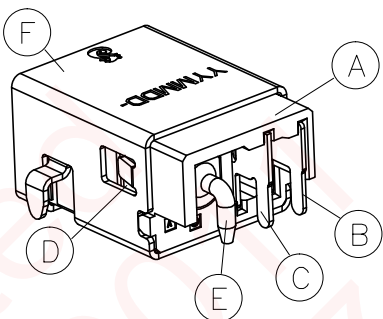
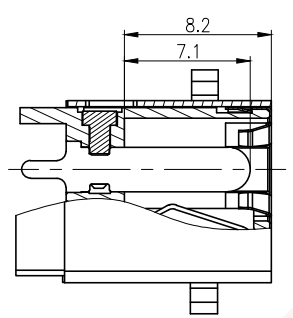
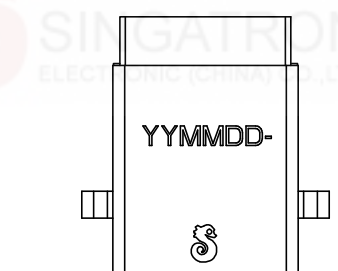
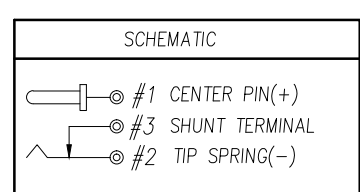
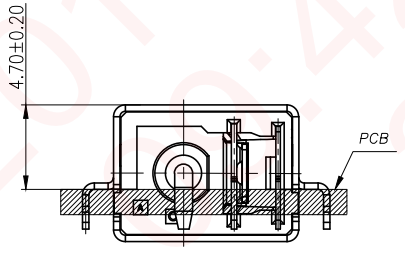
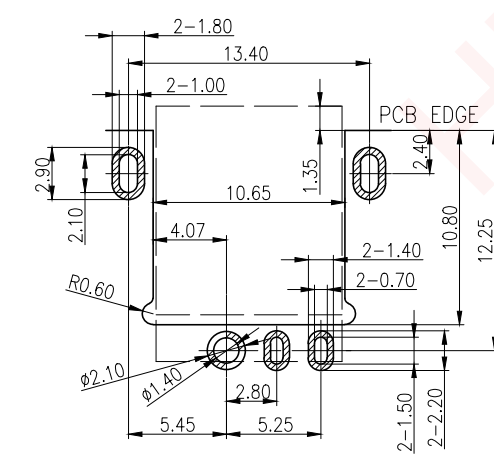
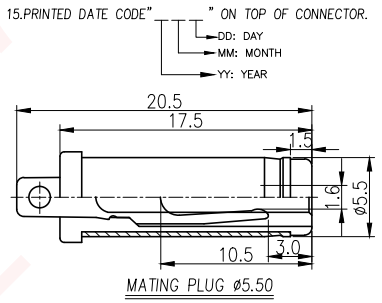
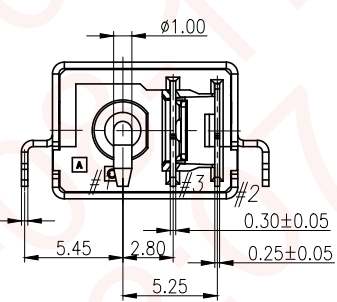
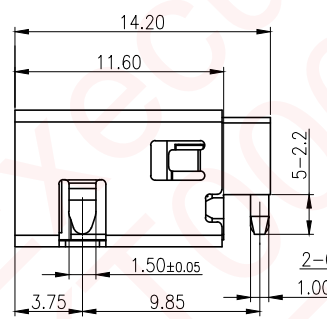
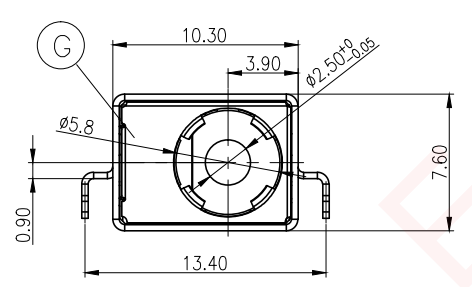


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
G	ECN NO: S150308-C	Ken	2015.3.9
H	ECN NO: S150206-C	Ken	2015.5.04
I	ECN NO: S150715-C	YUREN	2015.08.06



SPECIFICATIONS:

- RATING: DC 20V 12A
- INSERTION FORCE: 3.0KGF MAX  
WITHDRAWAL FORCE: 0.3KGF-3.0KGF
- INSULATION RESISTANCE BETWEEN ANY ADJACENT TERMINALS SHALL NOT BE LESS THAN 100 MEGOHMS BY 500 VOLTS.
- JACK SHALL WITHSTAND 500 VOLTS BETWEEN ANY ADJACENT TERMINAL FOR ONE MINUTE.
- CONTACT RESISTANCE SHALL NOT EXCEED 30mΩ
- JACK SHALL WITHSTAND 5,000 CYCLES OF INSERTION AND WITHDRAWAL WITH TESTING PLUG, AND CONTACT RESISTANCE SHALL NOT EXCEED 60mΩ.
- MEASURING CONDITION:  
TEMPERATURE: FROM 5°C TO 35°C. RELATIVE HUMIDITY: FROM 40% TO 85%
- ENVIRONMENTAL SPECIFICATIONS:  
8.1 HUMIDITY TEST: HUMIDITY 90% TO 95% TEMPERATURE 40°C ± 2°C FOR 96 HOURS.  
8.2 HEAT TEST: TEMPERATURE 70°C ± 2°C (HUMIDITY BELOW 50%) FOR 96 HOURS.  
8.3 COLD TEST: TEMPERATURE -40°C ± 2°C FOR 96 HOURS.
- SOLDERABILITY TEST: THE TERMINATION IS AT LEAST 95% COVERED BY A CONTINUOUS NEW SOLDER COATING.  
TEST CONDITION: DIP IN MOLTEN SOLDER FOR 5 Sec. AT 245±5°C (TERMINATION SHALL BE IMMERSED IN FLUX BEFORE TEST)



RECOMMEND P.C.B LAYOUT  
TOP VIEW (TOLERANCES: ±0.05)

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
G	GROUNDING	1	STAINLESS 0.1T	N/A
F	SHIELDING	1	BRASS 0.35T	Ni 60u"
E	PIN	1	BRASS	GOLD FALSH OVER Ni 50u"
D	STOPPER	1	HIGH TEMP. THERMOPLASTIC	N/A
C	SHUNT TERMINAL	1	BRASS STRIP 0.3T	GOLD FLASH ON CONTACT AREA; Sn 80u" ON SOLDER TAIL; ALL OVER Ni 60u"
B	TIP SPRING	1	COPPER ALLOY 0.25T	
A	BODY	1	LCP	BLACK

UNLESS OTHERWISE SPECIFIED TOLERANCES		Singatron Enterprise Co., Ltd. 信音企業股份有限公司			
DECIMALS:	ANGLES:	TITLE	DC JACK		
X : ±0.5	X : ±2°	DWN	YUREN	PART NO. 2DC3003-002211	
X.X : ±0.3	X.X : ±1°	CHKD	CERRY	SCALE 1:1	UNIT: mm
X.XX : ±0.2		APVD	LIAO	SIZE: A3	SHEET: 10F1
CUSTOMER COPY					